14.5 p-n Junction

A p-n junction is the basic building block of many semiconductor devices like diodes, transistor, etc. A clear understanding of the junction behaviour is important to analyse the working of other semiconductor devices. We will now try to understand how a junction is formed and how the junction behaves under the influence of external applied voltage (also called *bias*).

14.5.1 p-n junction formation

Consider a thin p-type silicon (p-Si) semiconductor wafer. By adding precisely a small quantity of pentavelent impurity, part of the p-Si wafer can be converted into n-Si. There are several processes by which a semiconductor can be formed. The wafer now contains p-region and n-region and a metallurgical junction between p-, and n- region.

Two important processes occur during the formation of a p-n junction: diffusion and drift. We know that in an n-type semiconductor, the concentration of electrons (number of electrons per unit volume) is more compared to the concentration of holes. Similarly, in a p-type semiconductor, the concentration of holes is more than the concentration of electrons. During the formation of p-n junction, and due to the concentration gradient across p-, and n- sides, holes diffuse from p-side to n-side (p \rightarrow n) and electrons diffuse from n-side to p-side (n \rightarrow p). This motion of charge carries gives rise to diffusion current across the junction.

When an electron diffuses from $n \to p$, it leaves behind an ionised donor on n-side. This ionised donor (positive charge) is immobile as it is bonded to the surrounding atoms. As the electrons continue to diffuse from $n \to p$, a layer of positive charge (or positive space-charge region) on n-side of the junction is developed.

Similarly, when a hole diffuses from $p \to n$ due to the concentration gradient, it leaves behind an ionised acceptor (negative charge) which is immobile. As the holes continue to diffuse, a layer of negative charge (or negative space-charge region) on the p-side of the junction is developed. This space-charge region on either side of the junction together is known as depletion region as the electrons and holes taking part in the initial

movement across the junction *depleted* the region of its free charges (Fig. 14.10). The thickness of depletion region is of the order of one-tenth of a micrometre. Due to the positive space-charge region on n-side of the junction and negative space charge region on p-side of the junction, an electric field directed from positive charge towards negative charge develops. Due to this field, an electron on p-side of the junction moves to n-side and a hole on n-side of the junction moves to p-side. The motion of charge carriers due to the electric field is called drift. Thus a drift current, which is opposite in direction to the diffusion current (Fig. 14.10) starts.

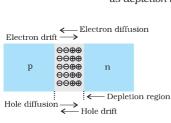


FIGURE 14.10 p-n junction formation process.

Initially, diffusion current is large and drift current is small. As the diffusion process continues, the space-charge regions on either side of the junction extend, thus increasing the electric field strength and hence drift current. This process continues until the diffusion current equals the drift current. Thus a p-n junction is formed. In a p-n junction under equilibrium there is *no net* current.

The loss of electrons from the n-region and the gain of electron by the p-region causes a difference of potential across the junction of the two regions. The polarity of this potential is such as to oppose further flow of carriers so that a condition of equilibrium exists. Figure 14.11 shows the p-n junction at equilibrium and the potential across the junction. The n-material has lost electrons, and p material has acquired electrons. The n material is thus positive relative to the p material. Since this potential tends to prevent the movement of electron from the n region into the p region, it is often called a barrier potential.

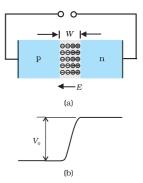


FIGURE 14.11 (a) Diode under equilibrium (V = 0), (b) Barrier potential under no bias.

Example 14.3 Can we take one slab of p-type semiconductor and physically join it to another n-type semiconductor to get p-n junction?

Solution No! Any slab, howsoever flat, will have roughness much larger than the inter-atomic crystal spacing (~2 to 3 Å) and hence *continuous contact* at the atomic level will not be possible. The junction will behave as a *discontinuity* for the flowing charge carriers.

EXAMPLE 14.8

14.6 SEMICONDUCTOR DIODE

A semiconductor diode [Fig. 14.12(a)] is basically a p-n junction with metallic contacts provided at the ends for the application of an external voltage. It is a two terminal device. A p-n junction diode is symbolically represented as shown in Fig. 14.12(b).

The direction of arrow indicates the conventional direction of current (when the diode is under forward bias). The equilibrium barrier potential can be altered by applying an external voltage V across the diode. The situation of p-n junction diode under equilibrium (without bias) is shown in Fig. 14.11(a) and (b).

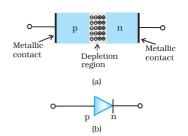


FIGURE 14.12 (a) Semiconductor diode, (b) Symbol for p-n junction diode.

14.6.1 p-n junction diode under forward bias

When an external voltage *V* is applied across a semiconductor diode such that p-side is connected to the positive terminal of the battery and n-side to the negative terminal [Fig. 14.13(a)], it is said to be *forward biased*.

The applied voltage mostly drops across the depletion region and the voltage drop across the p-side and n-side of the junction is negligible. (This is because the resistance of the depletion region – a region where there are no charges – is very high compared to the resistance of n-side and p-side.) The direction of the applied voltage (V) is opposite to the

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